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Mechanics of Solder Alloy Interconnects

The Mechanics of Solder Alloy Interconnects is a resource to be used in developing a solder joint reliability assessment. Each chapter is written to be used as a stand-alone resource for a particular aspect of materials and modeling issues. With this gained understanding, the reader in search of a solution to a solder joint reliability problem knows where in the materials and modeling communities to go for the appropriate answer.

213,99 €
199,99 € (zzgl. MwSt.)

Lieferfrist: bis zu 10 Tage

Artikelnummer: 9780442015053
Medium: Buch
ISBN: 978-0-442-01505-3
Verlag: Springer US
Erscheinungstermin: 31.01.1994
Sprache(n): Englisch
Auflage: 1994
Produktform: Gebunden
Gewicht: 1780 g
Seiten: 418
Format (B x H): 157 x 235 mm